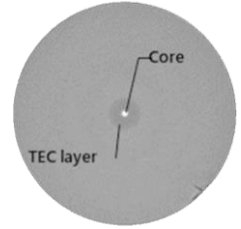


TEC SM fiber with heat resistant coating

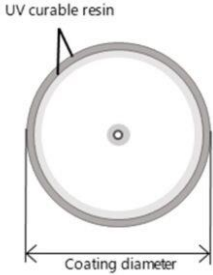
Fujikura TEC SM fibers with heat resistant coating can operate in a wide range of temperature between -40 °C and +150 °C. Fujikura fibers have a structure suitable for fusion splicing and optical connectors based on fiber design and manufacturing technologies developed over many years. Thermally-diffused Expanded Core (TEC) technology is applied to increase the mode field diameter by the heat generated during fusion bonding.



Features

- The fiber that has acrylate coating with improved heat resistance is available to use under the wide range of temperature between -40 °C and +150 °C.
- Low MFD mismatch loss between silicon waveguide and normal fiber
- Low fusion loss between TEC SM fiber and normal fiber
- Suitable for bonding with silicon photonics devices.

Specifications

	TEC13-15-U25HT-M4
Wavelength band	1310 nm band, 1550 nm band
Mode field diameter (μm)	3.4 ± 0.4 @ 1310 nm, 4.0 ± 0.3 @ 1550 nm
Concentricity error (μm)	≤ 0.5
Cladding diameter(Major diameter) (μm)	125 ± 1
Attenuation (dB/km)	≤ 50 @ 1310 nm, ≤ 35 @ 1550 nm
Cutoff wavelength (nm)	≤ 1280
Bending attenuation (dB, Φ5 mm × 10 turns)	≤ 0.01 @ 1550 nm
Minimum bending radius	2 % proof test level: R5 mm
Coating material	UV curable resin
Coating diameter (μm)	245 ± 15
Cross-section image	



Contact us